

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0739421200

Status:

Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Solder Tail, Open End, 144 Circuits

Documents:

[3D Model](#)

[Drawing \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

[73942](#)

Application

Backplane

Comments

Solder Tail

Component Type

PCB Header

Overview

[hdm](#)

Product Name

HDM®

Style

N/A

Physical

Circuits (Loaded)

144

Circuits (maximum)

144

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

No

Keying to Mating Part

None

Material - Metal

Phosphor Bronze

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Number of Columns

24

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length (in)

0.079 In

PC Tail Length (mm)

2.00 mm

PCB Retention

None

PCB Thickness Recommended (in)

0.098 In

PCB Thickness Recommended (mm)

2.50 mm

Packaging Type

Tube

Pitch - Mating Interface (in)

0.079 In

Pitch - Mating Interface (mm)

2.00 mm

Plating min: Mating (µin)

30

Plating min: Mating (µm)

0.75

Plating min: Termination (µin)

100

Plating min: Termination (µm)

2.5

Stackable

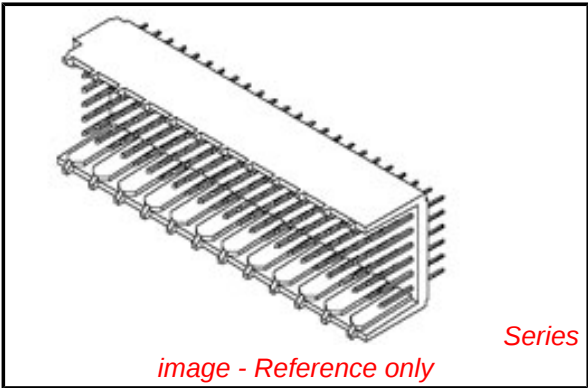
Yes

Surface Mount Compatible (SMC)

Yes

Temperature Range - Operating

-55°C to +105°C



EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73942Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

Termination Interface: Style

Through Hole

Electrical

Current - Maximum per Contact

1A

Data Rate

1.0 Gbps

Voltage - Maximum

250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification

PK-70873-0818

Sales Drawing

SD-73942-001

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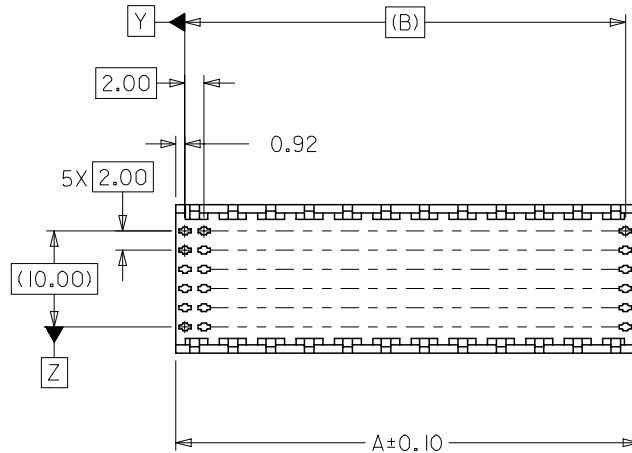
3

2

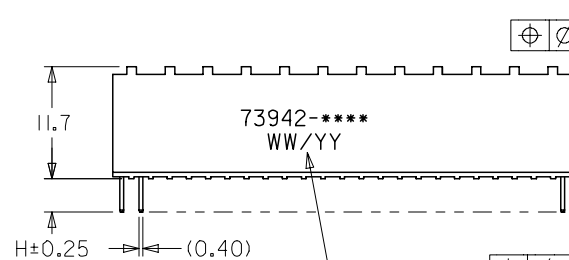
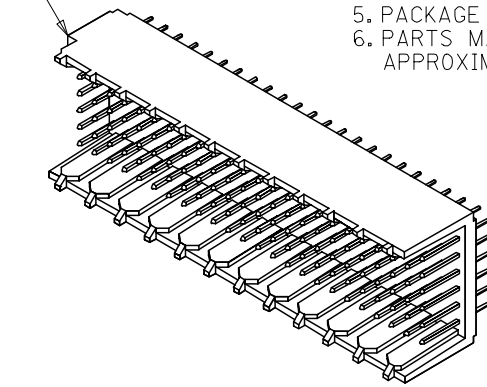
73942

NOTES:

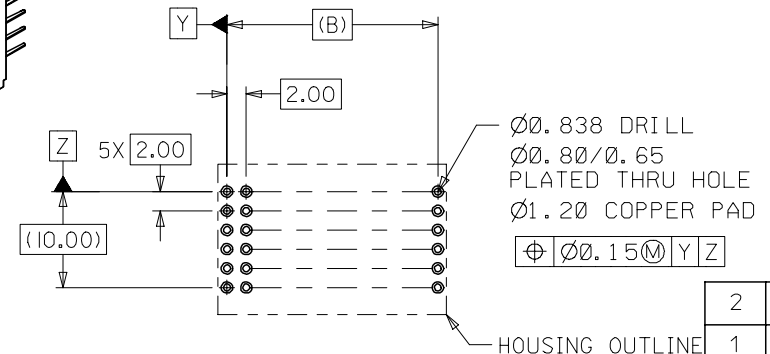
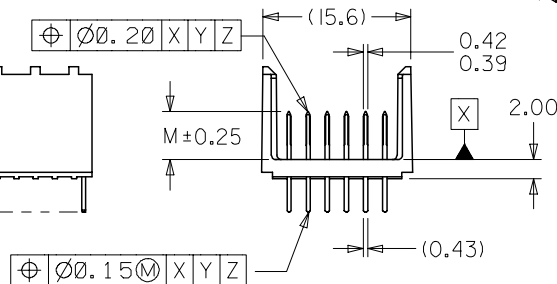
1. MATERIALS: HOUSING--LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94V-0, COLOR: BLACK,
TERMINAL: PHOSPHOR BRONZE.
2. FINISH: 0.75 MICROMETERS MINIMUM SELECTIVE GOLD (Au) IN MATING AREA;
2.50 MICROMETERS MINIMUM SELECTIVE TIN (Sn) IN TAIL AREA;
NICKEL (Ni) UNDERPLATE OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. PACKAGE PER PK-70873-0818.
6. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



LOCATING NOTCH



SEE NOTE 6



Ø0.838 DRILL
Ø0.80/Ø.65
PLATED THRU HOLE
Ø1.20 COPPER PAD
Ø0.15 (M) X Y Z

PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

2	A
1	G
SHT	REV

MODIFY FINISH NOTE EC NO: UCP2007-2259 DRAWN:MSI BARRA 2007/03/13 CHKD:BBARKER 2007/03/21 APPR:SMILLER 2007/03/22 G REV	DESCRIPTION QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	SALES ASSY HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION MOLEX INCORPORATED SD-73942-001 1 OF 2	
			mm	INCH	DRAWN BY JB INGHAM	DATE 1998/01/13	TITLE			
		4 PLACES	± ---	± ---	CHECKED BY	DATE				
		3 PLACES	± ---	± ---	SREED	1998/01/13				
		2 PLACES	± 0.05	± ---	APPROVED BY	DATE				
		1 PLACE	± 0.10	± ---	CBIXLER	1998/01/13	MOLEX	MOLEX INCORPORATED		
		ANGULAR ±1/2°		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART						
				SIZE B	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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2

1

MATERIAL NUMBER ASSIGNMENT

73942-* * 0 0

NUMBER	CIRCUIT SIZE	DIM "A"	DIM "B"	DIM "H"
0	72	23.84	22.00	2.0
1	144	47.84	46.00	2.0
2	72	23.84	22.00	2.5
3	144	47.84	46.00	2.5
4	72	23.84	22.00	3.0
5	144	47.84	46.00	3.0
6	72	23.84	22.00	3.5
7	144	47.84	46.00	3.5

NUMBER	DIM "M"
0	5.0
1	5.5
2	6.0

SEE SHEET 1 EC No. U81577 DRWN:JBINGHAM 98/0203 CHK: SREED 98/0203 APPR:CBIXLER 98/0203 A	DESCRIPTION REV	QUALITY SYMBOLS MAJOR =0 CRITICAL C=0	GENERAL TOLERANCES: (UNLESS SPECIFIED)		SCALE --:--	DESIGN UNITS ☒ mm ☐ INCH	THIRD ANGLE PROJECTION	DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT	REV		
					DRAWN BY & DATE JBINGHAM 98/01/13			TITLE: SALES ASSY, HDM BACKPLANE OPEN END OPTION SOLDER TAIL VERSION		MOLEX INCORPORATED	MATERIAL NO. SEE CHART	DRAWING NO. SD-73942-001	SHEET NO. 2
					CHECKED BY & DATE SREED 98/01/13								
					APPROVED BY & DATE CBIXLER 98/01/13								
					CAD FILENAME S73942X2.DGN			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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